

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1764efe-1.5#trpbf

(Engineering Calculation)

TSSOP Exp. Pad

(printed on: 2020-07-11 18:22:13)

**TOTAL MASS (g) : 0.070665**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005437	1000000	76940.5859375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025576	975000	361933.5		
		Iron (Fe)	7439-89-6	0.000630	24000	8915.31640625		
		Phosphorus (P)	7723-14-0	0.000008	300	113.210357666		
		Zinc (Zn)	7440-66-6	0.000018	700	254.723297119		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.026232</b>	<b>1000000</b>	<b>371216.78125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002364	1000000	33452.3828125		
		<b>External Plating Total:</b>				<b>0.002364</b>	<b>1000000</b>	<b>33452.3828125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001030	1000000	14575.8339844		
<b>Internal Plating Total:</b>				<b>0.001030</b>	<b>1000000</b>	<b>14575.8339844</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001372	750000	19415.5761719		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000457	250000	6467.14160156		
<b>Die Attach Total:</b>				<b>0.001829</b>	<b>1000000</b>	<b>25882.7167969</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	68987.5625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.026650	820000	377132		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000813	25000	11505.0029297		
		Carbon Black (C)	1333-86-4	0.000163	5000	2306.66113281		
		<b>Encapsulation Total:</b>				<b>0.032501</b>	<b>1000000</b>	<b>459931.25</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001272	1000000	18000.4453125		
					<b>TOTAL MASS (g) :</b>	<b>0.070665</b>		